# **GS2858 Series**

# **GS2858 Series**

# 500mA Low IQ High PSRR LDO Linear Regulator

### **Product Description**

The GS2858 series is a Sub-µA power consumption, high accuracy, low drop-out voltage regulator with Chip Enable Pin, high ripple rejection and fast discharge function.

The GS2858 series is available in SOT-23, SOT-23-5L and DFN1x1-4L package.

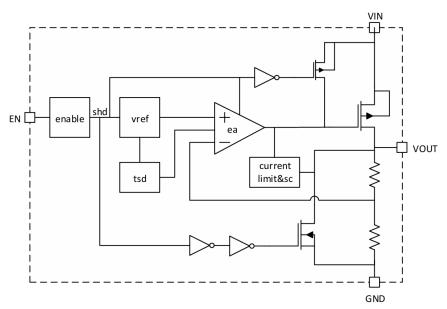
### **Features**

- Max Input Voltage 6V
- Output Accuracy: ±1.5%
- Low Power Consumption: 0.7µA (Typical)
- High PSRR: 90dB@1KHz, 10mA
- Available in SOT-23, SOT-23-5L and
- DFN1x1-4L Packages
- RoHS Compliant and Halogen Free

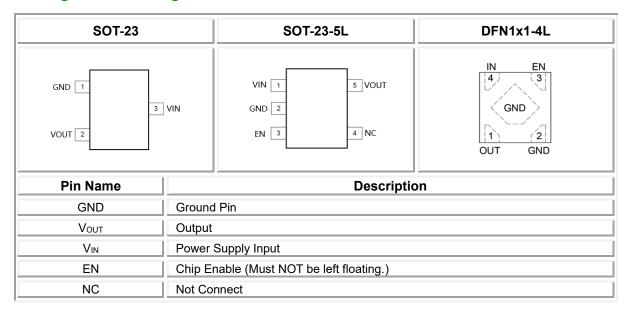
### **Applications**

- Portable and Battery-Powered Equipment
- IP Cameras
- Ultra Low Power Applications

### **Functional Block Diagram**



### **Packages & Pin Assignments**



### **Ordering and Marking Information**

	Ordering Information						
,, , l	SOT-23		SOT-	SOT-23-5L		DFN1x1-4L	
Vout	P/N	Marking	P/N	Marking	P/N	Marking	
1.2V	*GS2858JZ12F	5812	GS2858L12F	LW5812	*GS2858F12F	58C	
1.8V	*GS2858JZ18F	5818	GS2858L18F	LW5818	GS2858F18F	58G	
2.8V	*GS2858JZ28F	5828	GS2858L28F	LW5828	GS2858F28F	58J	
3.3V	GS2858JZ33F	5833 🗆 🗆	GS2858L33F	LW5833	GS2858F33F	58M	
5.0V	*GS2858JZ50F	GS2858JZ50F 5850		LW5850	*GS2858F50F	58T	
NOTE: Please	NOTE: Please check the availability of the one marked * with sales representative.						
	Quantity/Reel						
	SOT-23		SOT-23-5	SL	DFN1x1	I-4L	
	3,000 PCS		3,000 PC	S	10,000 F	PCS	



GS2858 11 12 2 F

**Product Code:** 

GS2858

Package Code:

1 1 is JZ, L and F

- JZ is SOT-23

- L is SOT-23-5L

- F is DFN1x1-4L

Voltage Code:

22 is 12, 18, 33 and so on.

12 for 1.2V, 18 for 1.8V, 33 for 3.3V and so on.

Green Level:

**F** stands for RoHS Compliant and Halogen Free

### **Marking Information**

Package	Marking
SOT-23	58 1 1 2 2
SOT-23-5L	LW58111 22222
DFN1x1-4L	58 3

Product Code: - 58 or LW58 Voltage Code:

1 is 12, 18, 33 and so on.

3 is B, C and G etc.

- 12 or C for 1.2V

18 or G for 1.8V28 or J for 2.8V

- 33 or M for 3.3V

- 50 or T for 5.0V

GS Code:

2 digits are GS Code



### Absolute Maximum Ratings <sup>1</sup> (T<sub>A</sub>=25°C, unless otherwise specified)

Symbol	Parameter	Rating	Units	
Vin	Supply Voltage		7	V
VEN	Enable Pin Voltage		7	V
		SOT-23	490	
P <sub>D</sub>	Maximum Power Dissipation <sup>3</sup>	SOT-23-5L	540	mW
	DFN1x1-4L		550	
	Thermal Resistance, Junction to Ambient <sup>3</sup>	SOT-23	255	°C/W
R <sub>eJA</sub>		SOT-23-5L	230	
	DFN1x1-4L		226	
TJ	Maximum Junction Temperature		-40 - 150	°C
T <sub>STG</sub>	Storage Temperature Range		-40 - 150	°C
TLEAD	Lead Temperature (Soldering 10sec)		260	°C

### NOTE:

- Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.
  These are stress ratings only, and functional operation of the device at these or any other conditions beyond
  those indicated under Recommended Operating Conditions is not implied. Exposure to
  absolute-maximum-rated conditions for extended periods may affect device reliability
- 2. Per ANSI/ESDA/JEDEC JS-001
- 3. Device mounted on FR-4 PCB

### **Recommended Operating Range**

Symbol	Parameter	Value	Units
V <sub>IN</sub>	Max V <sub>IN</sub> Supply Voltage	6	V
V <sub>EN</sub>	EN Pin Voltage	0 - 6	V
Іоит	Output Current	0 - 500	mA
ΤJ	Operating Junction Temperature Range	-40 - 125	°C



### **Electrical Characteristics** (T<sub>A</sub> =25°C, unless otherwise specified.)

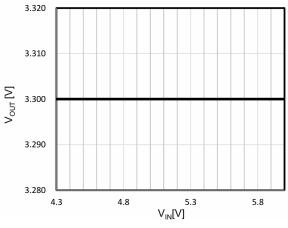
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Vin	Input Voltage		-	-	6	V
Vout	Output Accuracy	I <sub>OUT</sub> = 1mA	-1.5	-	+1.5	%
I <sub>LIM</sub>	Current Limit <sup>4</sup>	V <sub>IN</sub> =4.3V, V <sub>OUT</sub> =3.3V	530	750	-	mA
lα	Quiescent Current	V <sub>IN</sub> =V <sub>EN</sub> =V <sub>OUT</sub> +1V, No Load	-	0.7	1	μA
I <sub>SHD</sub>	Shutdown Current	V <sub>IN</sub> ==6V , V <sub>EN</sub> =0V	-	-	0.1	μA
		I <sub>OUT</sub> =500mA, V <sub>OUT</sub> =1.2V	-	1200	-	
$V_{DROP}^{5}$	Dropout Voltage	I <sub>OUT</sub> =500mA, V <sub>OUT</sub> =2.8V	-	530	-	mV
		I <sub>OUT</sub> =500mA, V <sub>OUT</sub> =3.3V	-	450	-	
RLINE	Line Regulation	$V_{IN}$ = $V_{OUT}$ +1V to 6V, $I_{OUT}$ =1mA	-	0.2	0.5	%/V
RLOAD	Load Regulation	I <sub>OUT</sub> =1mA to 500mA	-	0.004	0.01	%/mA
PSRR	Power Supply Rejection Ratio	C <sub>IN</sub> None, I <sub>OUT</sub> =10mA, f=1KHz	-	90	-	dB
t <sub>st</sub>	Startup Time	From VEN 'L'→'H' to 95%*Vout, Couт=1uF, No Load	-	0.4	-	ms
I <sub>SHORT</sub>	Short Current	$V_{IN} > 3V$ , $V_{OUT} = 0V$	-	90	-	mA
V <sub>ENH</sub>	EN High Voltage	V = 0V	1.5	-	-	V
V <sub>ENL</sub>	EN Low Voltage	V <sub>IN</sub> ==6V	-	_	0.5	V
T <sub>SD</sub>	Thermal Shutdown	Temperature rising	-	165	-	°C
$\triangle T_{SD}$	T <sub>SD</sub> Hysteresis	Temperature falling	-	30	-	°C
R <sub>DSG</sub>	R <sub>ON</sub> of Discharge MOSFET	V <sub>IN</sub> = 6V, V <sub>EN</sub> =0V	-	100	-	Ω

### NOTE:

- 4. Guaranteed by design
  5. The dropout voltage is defined as V<sub>IN</sub> V<sub>OUT</sub>, when V<sub>OUT</sub> =95% x V<sub>OUT(NOM)</sub>

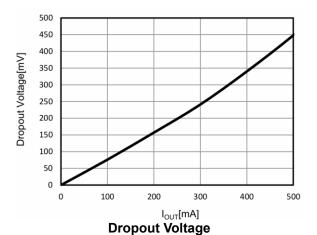


### Performance Characteristics (T<sub>A</sub> =25°C, unless otherwise specified.)

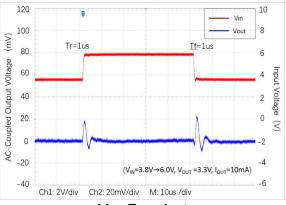


**Line Regulation** 

 $(V_{OUT} = 3.3V, I_{OUT} = 1 \text{ mA}, V_{IN} = 4.3V \text{ to } 6.0V)$ 

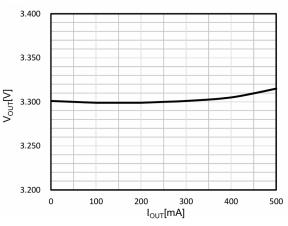


 $(V_{OUT} = 3.3V*0.95, I_{OUT} = 0mA to 500mA,)$ 



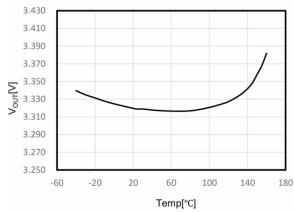
Line Transient

 $(V_{OUT} = 3.3V, I_{OUT} = 10mA, V_{IN} = 3.8V \text{ to } 6.0V)$ 



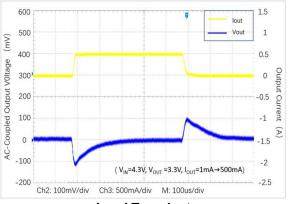
### **Load Regulation**

( $V_{OUT}$  =3.3V,  $I_{OUT}$ =0mA to 500mA,  $V_{IN}$ =4.3V)



**V**<sub>OUT</sub> vs. Temperature

( $V_{OUT}=3.3V$ ,  $I_{OUT}=1mA$ ,  $V_{IN}=4.3V$ )

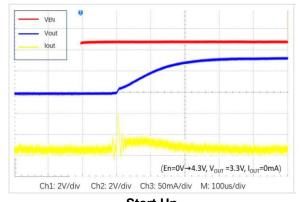


**Load Transient** 

 $(V_{OUT} = 3.3V, I_{OUT} = 1 \text{mA to } 500 \text{mA}, V_{IN} = 4.3V)$ 

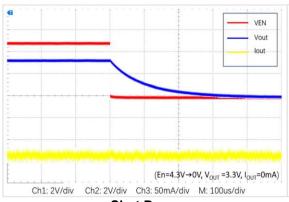


### **Performance Characteristics (Continued)**



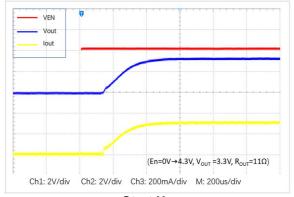
Start Up

( $V_{OUT} = 3.3V$ ,  $I_{OUT} = 0$ mA,  $V_{EN} = 0V$  to.4.3V)



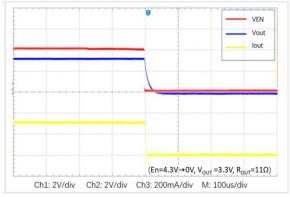
**Shut Down** 

(Vout =3.3V, Iout=0mA, Ven=4.3V to 0V)



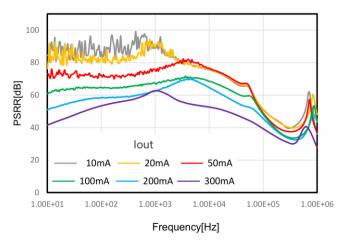
Start Up

 $(V_{OUT} = 3.3V, I_{OUT} = 300mA, V_{EN} = 0V to.4.3V)$ 



### **Shut Down**

(Vout =3.3V, Iout=300mA, Ven=4.3V to 0V)

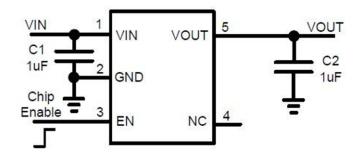


**PSRR** 

(Vout =3.3V, C<sub>IN</sub>=None, C<sub>OUT</sub> =1uF. V<sub>IN</sub>=4.3V, V<sub>PP</sub> =1.0V,)



### **Typical Application Circuit**



### **Input Capacitor Selection**

Like any low-dropout regulator, the external capacitors used with the GS2858 Series must be carefully selected for regulator stability and performance. Using a capacitor whose value is  $>=1\mu F$  on the GS2858 Series input and the amount of capacitance can be increased without limit. An at least 10uF input capacitor is needed if input ripple voltage  $V_{PP}>1V$ . The input capacitor must be located a distance less than 0.5 inch from the input pin of the IC and returned to a clean analog ground. Any good quality ceramic or tantalum can be used for this capacitor. The capacitor with larger value and lower ESR (equivalent series resistance) provides better PSRR and line-transient response.

### **Output Capacitor Selection**

The output capacitor must meet both requirements for minimum amount of capacitance and ESR in all LDOs application. The GS2858 Series is designed specifically to work with low ESR ceramic output capacitor in space-saving and performance consideration. Using a ceramic capacitor whose value is at least  $1\mu F$  on the GS2858 Series output ensures stability. An appropriate output capacitor can reduce noise and improve load transient response and PSRR. The output capacitor should be located not more than 0.5 inch from the  $V_{OUT}$  pin of the GS2858 Series and returned to a clean analog ground.

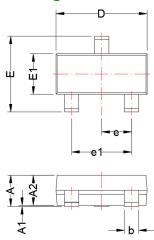
### Layout Recommendation

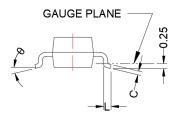
To improve ac performance such as PSRR, output noise, and transient response, it is recommended that the PCB be designed with separate ground planes for  $V_{IN}$  and  $V_{OUT}$ , with each ground plane connected only at the GND pin of the device.



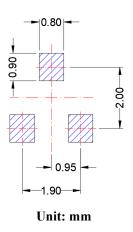
# **SOT-23**

## **Package Dimension**





### **Recommended Land Pattern**



	Dimensions						
0	Millimeters		Inches				
Symbol	MIN	MAX	MIN	MAX			
Α	0.75	1.17	0.030	0.046			
<b>A</b> 1	0.01	0.15	0.000	0.006			
A2	0.70	1.02	0.028	0.040			
b	0.30	0.50	0.012	0.020			
С	0.08	0.20	0.003	0.008			
D	2.80	3.04	0.110	0.120			
E	2.10	2.64	0.083	0.104			
E1	1.20	1.40	0.047	0.055			
е	0.95	BSC	0.037 BSC				
e1	1.90 BSC 0.075 BSC			BSC			
L	0.30	0.60	0.012	0.024			
θ	0°	8°	0°	8°			

### NOTE:

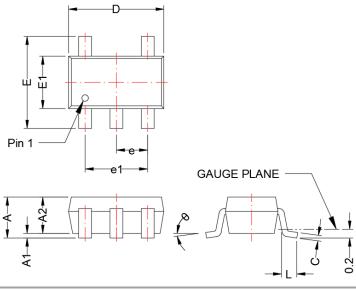
Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

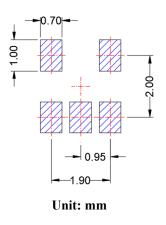


# SOT-23-5L

# **Package Dimension**

# **Recommended Land Pattern**





	Dimensions				
Cumbal	Millimeters		Inches		
Symbol	MIN	MAX	Min	MIN	
Α	0.90	1.45	0.035	0.057	
A1	0.00	0.15	0.000	0.006	
A2	0.90	1.30	0.035	0.051	
b	0.30	0.50	0.012	0.020	
С	0.08	0.26	0.003	0.010	
D	2.70	3.10	0.106	0.122	
E	2.20	3.00	0.087	0.118	
E1	1.30	1.75	0.051	0.069	
е	0.95	BSC	0.037 BSC		
e1	1.90 BSC 0.075 BSC		BSC		
L	0.3	0.6	0.012 0.024		
$\theta$	0°	8°	0°	8°	

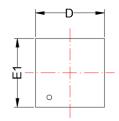
### NOTE:

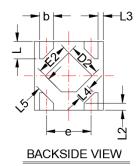
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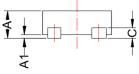


# DFN1x1-4L

# **Package Dimension**

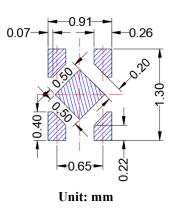








### **Recommended Land Pattern**



	Dimensions					
	Millin	neters	Inches			
Symbol	MIN	MAX	MIN	MAX		
Α	0.35	0.40	0.014	0.016		
<b>A</b> 1	0.00	0.05	0.000	0.002		
b	0.15	0.25	0.006	0.010		
С	0.127	REF	0.005 REF			
D	0.95	1.05	0.037 0.041			
D2	0.38	0.58	0.015	0.023		
E1	0.95	1.05	0.037	0.041		
E2	0.38	0.58	0.015	0.023		
е	0.65 BSC		0.026 BSC			
L	0.20	0.30	0.008 0.012			
L2	0.103 REF		0.004 REF			
L3	0.075	REF	0.003 REF			
L4	0.208 REF		0.008 REF			
L5	0.200	) REF	0.008 REF			

### NOTE:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



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